

Vishay Siliconix

# Automotive Dual N-Channel 75 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	75			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.050			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.066			
I <sub>D</sub> (A) per leg	8			
Configuration	Dual			

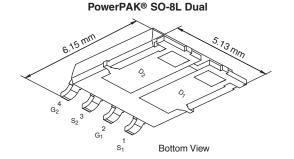
### **FEATURES**

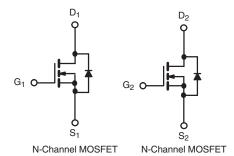
- TrenchFET® Power MOSFET
- AEC-Q101 Qualified<sup>d</sup>
- 100 % Rq and UIS Tested
- Material categorization:
  For definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>





ROHS COMPLIANT HALOGEN FREE





ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ980AEP-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	s otherwise noted	)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	75		
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current <sup>a</sup>	T <sub>C</sub> = 25 °C	1	17		
Continuous Drain Current-	T <sub>C</sub> = 125 °C	I <sub>D</sub>	10		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	30	Α	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	68		
Single Pulse Avalanche Current		I <sub>AS</sub>	14		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	10	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	34	10/	
waximum Power Dissipation	T <sub>C</sub> = 125 °C	P <sub>D</sub>	11	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature) <sup>e, f</sup>			260		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient F	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	85	°C/W
Junction-to-Case (Drain)		$R_{thJC}$	4.3	C/VV

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.
- e. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection..
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				l			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		75	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.8 A	-	0.041	0.050	
Drain-Source On-State Resistance <sup>a</sup>	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.8 A, T <sub>J</sub> = 125 °C	-	-	0.089	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.8 A, T <sub>J</sub> = 175 °C	-	-	0.116	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 3.3 A	-	0.055	0.066	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 3.8 A	-	14	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	630	790	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 35 \text{ V}, f = 1 \text{ MHz}$	-	84	105	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	36	45	
Total Gate Charge <sup>c</sup>	Qg			-	14	21	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 35 \text{ V}, I_{D} = 9.7 \text{ A}$	-	2.3	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	2.9	-	
Gate Resistance	R <sub>g</sub>		f = 1 MHz	1.3	2.67	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	9	14	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> :	= 35 V, $R_L = 35 \Omega$	-	10	15	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 1 A, Y$	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	16	24	1113
Fall Time <sup>c</sup>	t <sub>f</sub>	]		-	12	18	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	68	Α
Forward Voltage	V <sub>SD</sub>	$I_F = 2.4 \text{ A}, V_{GS} = 0$		-	0.8	1.1	V

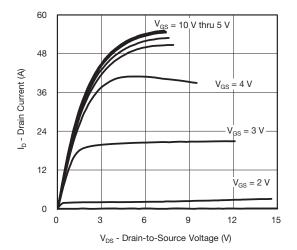
### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

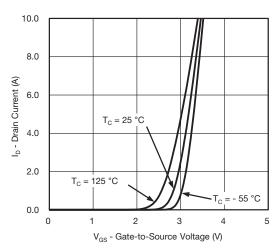
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



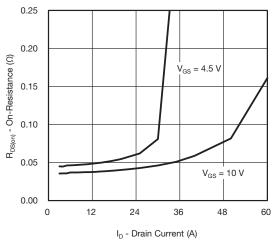
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



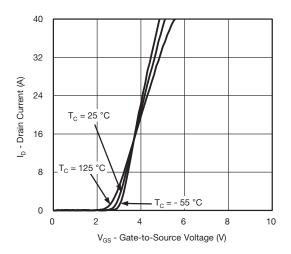
### **Output Characteristics**



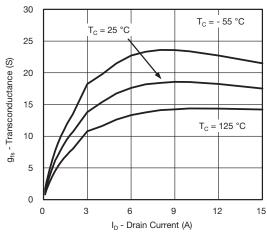
#### **Transfer Characteristics**



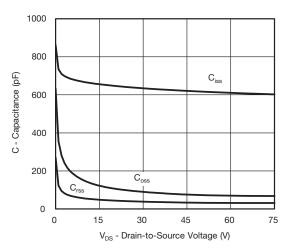
On-Resistance vs. Drain Current



### **Transfer Characteristics**



### Transconductance

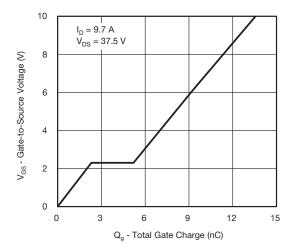


Capacitance

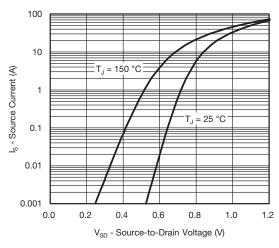
150 175



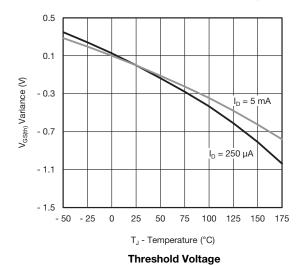
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



### **Gate Charge**



### **Source Drain Diode Forward Voltage**



2.5 I<sub>D</sub> = 20 A R<sub>DS(on)</sub> - On-Resistance (Normalized) 2.1  $V_{GS} = 4.5 \text{ V}$ 1.7  $V_{GS} = 10 \text{ V}$ 1.3

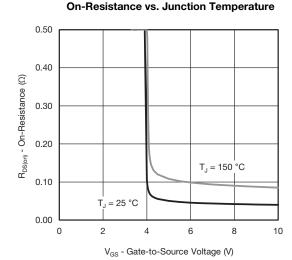
0.9

0.5

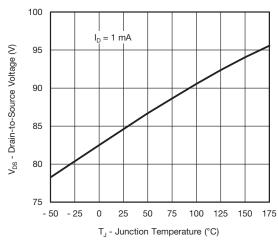
- 50

- 25 Ω 25 50 75 100 125

T<sub>J</sub> - Junction Temperature (°C)



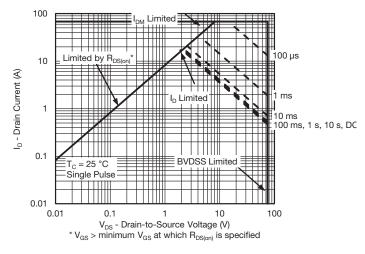
### On-Resistance vs. Gate-to-Source Voltage



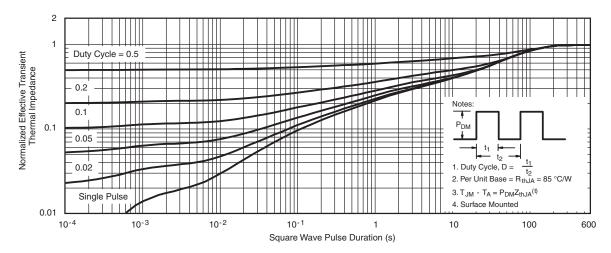
Drain Source Breakdown vs. Junction Temperature



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



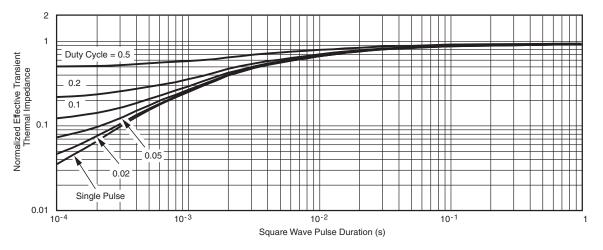
### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

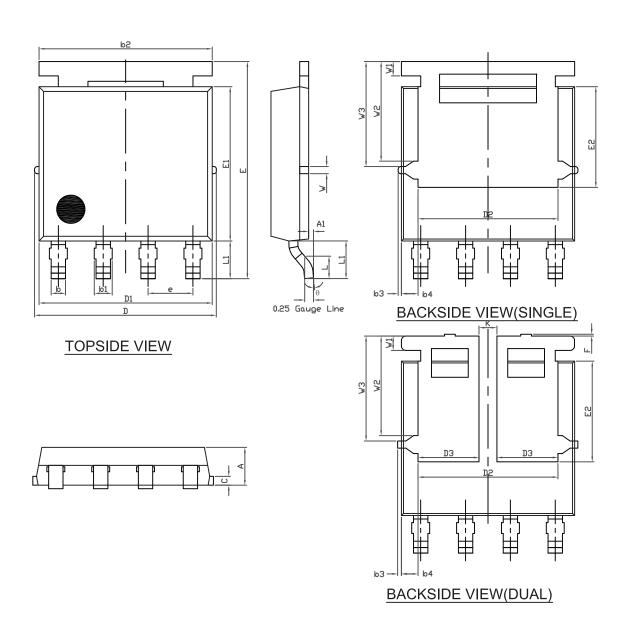
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?62833">www.vishay.com/ppg?62833</a>.





# PowerPAK® SO-8L Case Outline





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Vishay Siliconix

DIM.		MILLIMETERS		INCHES		
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
А	1.00	1.07	1.14	0.039	0.042	0.045
A1	0.00	-	0.127	0.00	-	0.005
b	0.33	0.41	0.48	0.013	0.016	0.019
b1	0.44	0.51	0.58	0.017	0.020	0.023
b2	4.80	4.90	5.00	0.189	0.193	0.197
b3		0.094			0.004	
b4		0.47			0.019	
С	0.20	0.25	0.30	0.008	0.010	0.012
D	5.00	5.13	5.25	0.197	0.202	0.207
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.86	3.96	4.06	0.152	0.156	0.160
D3	1.63	1.73	1.83	0.064	0.068	0.072
е		1.27 BSC		0.050 BSC		
Е	6.05	6.15	6.25	0.238	0.242	0.246
E1	4.27	4.37	4.47	0.168	0.172	0.176
E2 (for Al product)	2.75	2.85	2.95	0.108	0.112	0.116
E2 (for other product)	3.18	3.28	3.38	0.125	0.129	0.133
F	-	-	0.15	-	-	0.006
L	0.62	0.72	0.82	0.024	0.028	0.032
L1	0.92	1.07	1.22	0.036	0.042	0.048
K		0.51		0.020		
W	0.23		0.009			
W1	0.41		0.016			
W2	2.82		0.111			
W3		2.96		0.117		
θ	0°	-	10°	0°	-	10°

ECN: C12-0026-Rev. B, 27-Aug-12

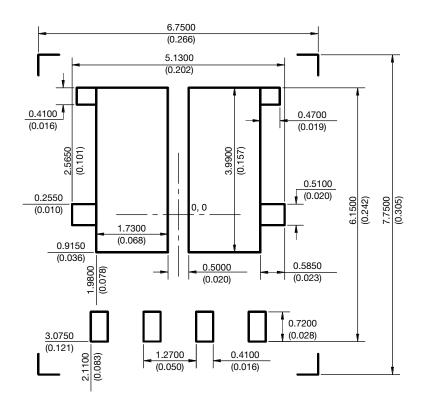
DWG: 5976

#### Note

· Millimeters will gover



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



## **Legal Disclaimer Notice**

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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

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Revision: 02-Oct-12 Document Number: 91000

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